



## General Description

The IRF7351PbF use advanced SGT MOSFET technology to provide low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in

## General Features

$V_{DS} = 60V$   $I_D = 15A$

$R_{DS(ON)} < 15m\Omega$  @  $V_{GS} = 10V$

## Applications

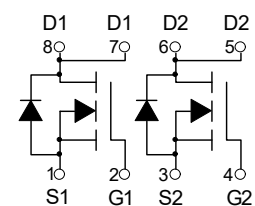
Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications



SOP-8  
(SOIC-8)



Dual N-Channel MOSFET

## Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IRF7351PbF	SOP-8(SOIC-8)	HXY MOSFET	3000

## Absolute Maximum Ratings at $T_J = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	60	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup>	$I_D$	15	A
Pulsed drain current <sup>2)</sup>	$I_{D, pulse}$	180	A
Power dissipation <sup>3)</sup>	$P_D$	60	W
Single pulsed avalanche energy <sup>5)</sup>	EAS	36	mJ
Operation and storage temperature	$T_{stg}, T_J$	-55 to 150	$^\circ C$
Thermal resistance, junction-case	$R_{\theta JC}$	2.5	$^\circ C/W$



### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.6	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	12	15	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	15	20	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	930	-	pF
C <sub>oss</sub>	Output Capacitance		-	230	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	8	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	22	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	4.5	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	3.5	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =20A, R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V	-	4.5	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	2.7	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	13.8	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	2.7	-	ns
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	15	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	180	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>F</sub> =20A, di/dt=100A/μs	-	18	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	12	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

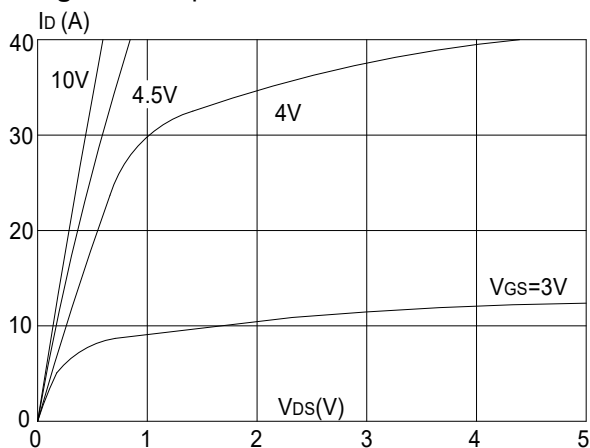
2. EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=12A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

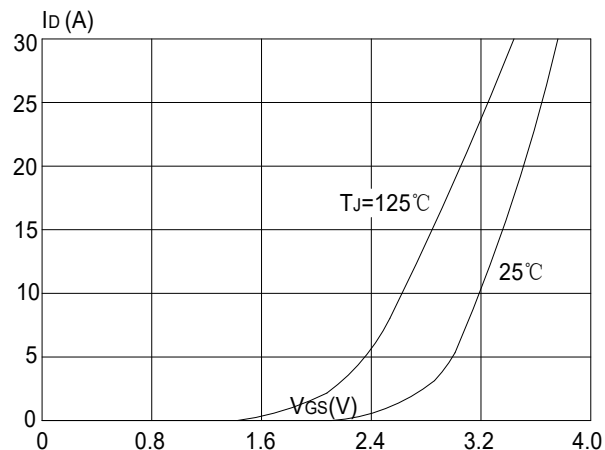


## Typical Performance Characteristics

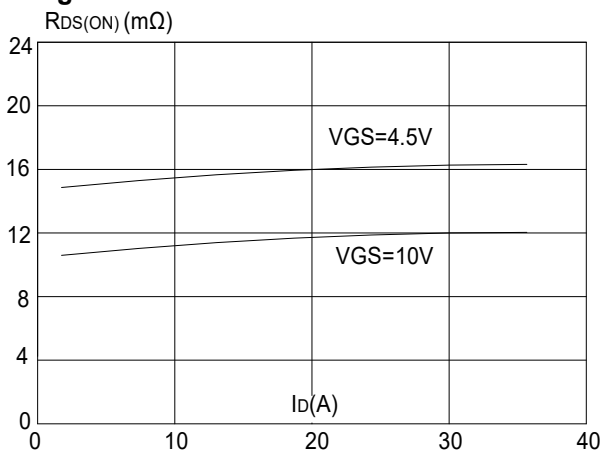
**Figure1: Output Characteristics**



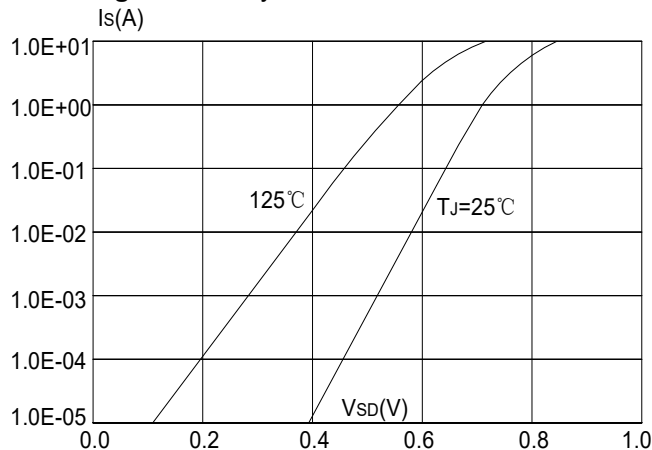
**Figure 2: Typical Transfer Characteristics**



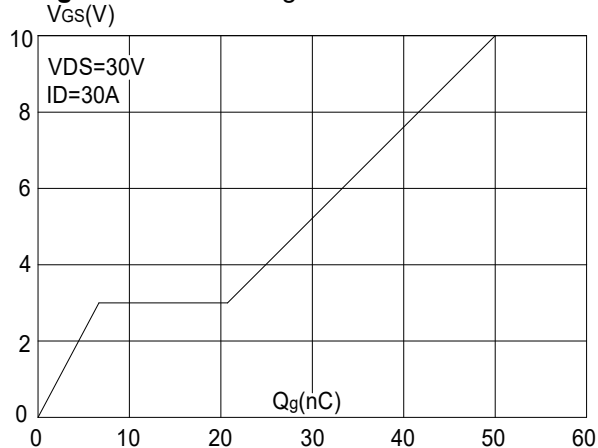
**Figure 3: On-resistance vs. Drain Current**



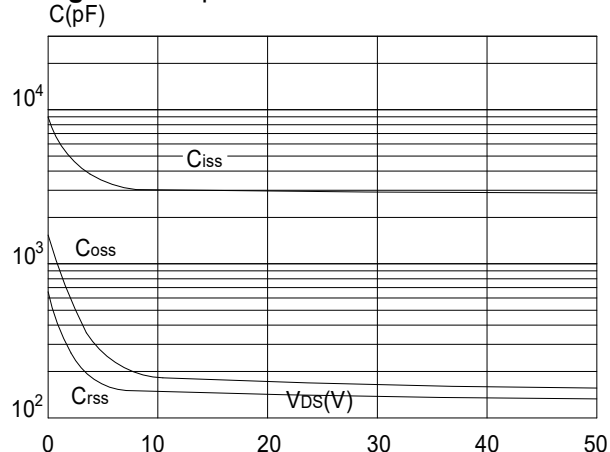
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

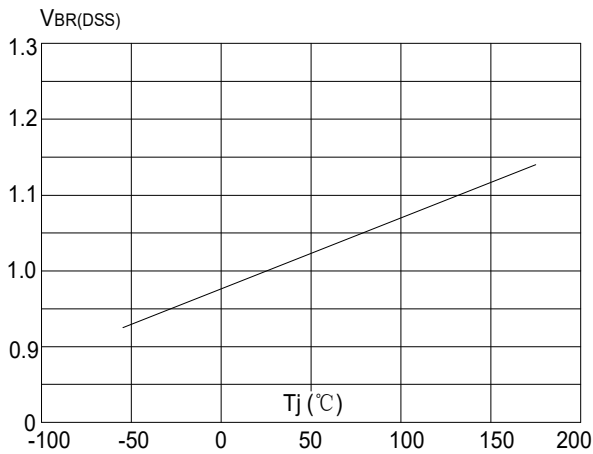


**Figure 6: Capacitance Characteristics**

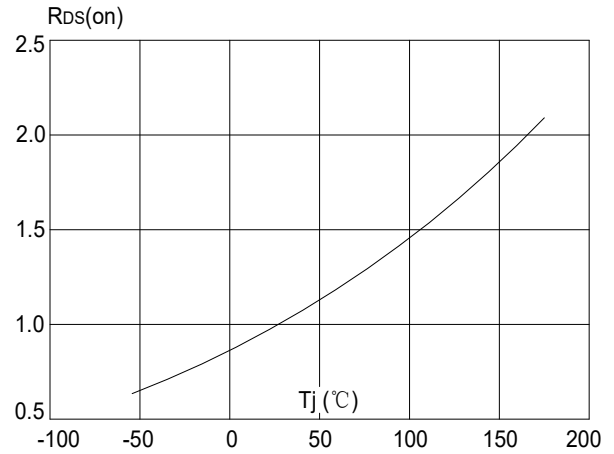




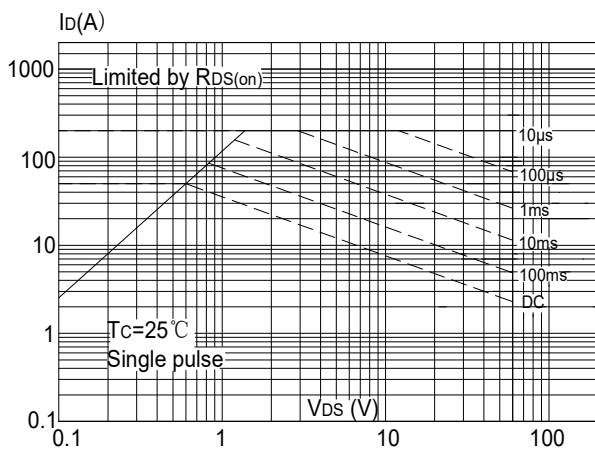
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



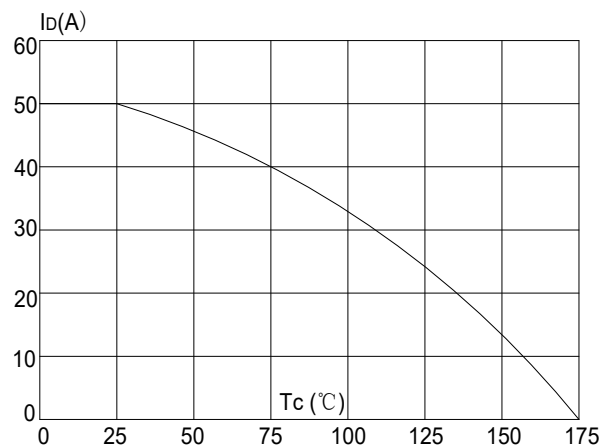
**Figure 8:** Normalized on Resistance vs. Junction Temperature



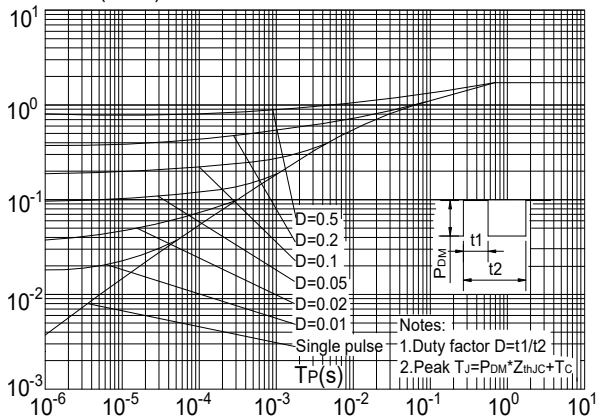
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

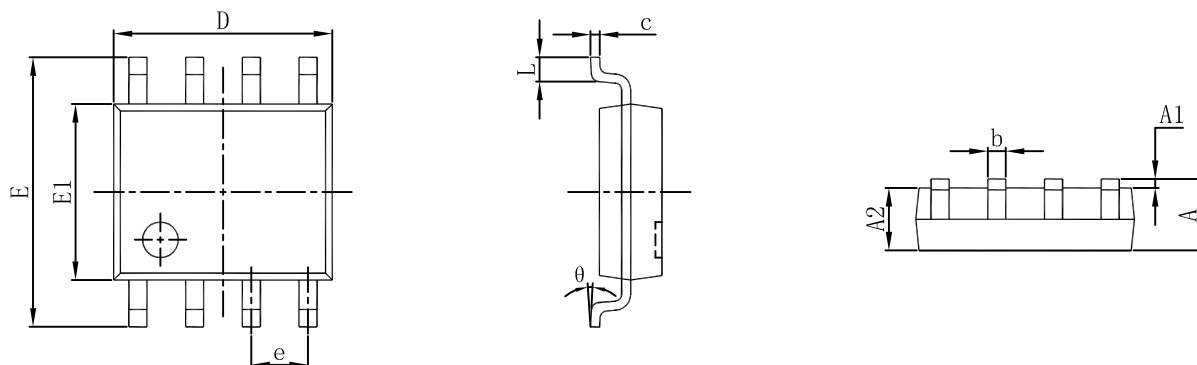


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

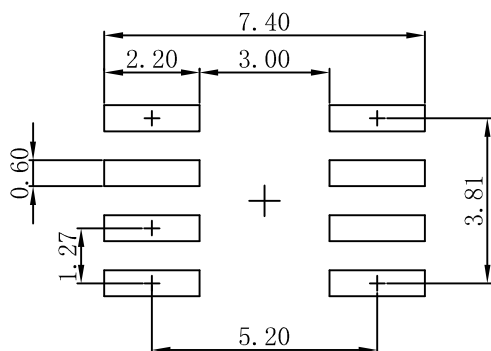




## SOP-8(SOIC-8) Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Note:  
1. Controlling dimension: in millimeters.  
2. General tolerance:  $\pm 0.05\text{mm}$ .  
3. The pad layout is for reference purposes only.



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